8020
FULLY AUTOMATIC TWIN

ADT 8020 Dicing system has two facing spindles that can simultaneously dice wafers at high throughput. ADT 8020 is a high accuracy system that can dice product up to 8" in diameter, at high performances and low cost of operation.

FEATURES & BENEFITS

- Flexibility **-** Supports Hub and Hubless blades up to 3" O.D.
- Spindles of 1.8 kW or 2.4 kW high power (for challenging applications)
- Intuitive operation interface using a large 19" touch screen monitor
- Fast & simple blade change with a locking spindle shaft
- SECS / GEM platform ready

Specifications		8020
Workpiece Size		Ø 8"
Spindle		Two facing spindles, Max. 60,000 rpm / 1.2 KW
Blade Size		2" - 3"
Y1 / Y2 Axis,	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis		Air Slide
Z1 / Z2 Axis,	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. stroke	30 mm (for 2.188" blade OD)
θ Axis,	Repeatability	4 arc-sec
	Stroke	350°
Cleaning Station		Full rinse and dry cycle
	Spinning speed	100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
Utilities,	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm	1,015 x 1,460 x 1,820
	Weight	1300 kg

Note: Specifications are subject to change without notice.

7900 8" Duo
AUTOMATIC TWIN

ADT 7900 series has two facing spindles that can simultaneously dice wafers or packages at high throughput. ADT 7900 series is a high accuracy system that can dice product at high performances and low cost of operation.

Basic machine models:

- 7900 Duo up to 8" wafer

FEATURES & BENEFITS

- Flexibility **-** Supports Hub and Hubless blades up to 3" O.D.
- Spindles of 2.4 kW high power (for challenging applications)
- Superior vision system with continuous zoom magnification
- Intuitive operation interface using a large 17" touch screen monitor
- Small foot print

Specifications		7900 Duo 8"
Workpiece Size		Ø 8"
Spindle		Two facing spindles, Max. 60,000 rpm / 1.2 KW
Blade Size		2" - 3"
Y1 / Y2 Axis,	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis		Air Slide
Z1 / Z2 Axis,	Resolution	0.2 µm
	Repeatability	1.0 µm
	Stroke	30 mm (for 2.188" blade OD)
θ Axis,	Repeatability	4 arc-sec
	Stroke	350°
Utilities,	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm	875 x 975 x 1450
	Weight	900 kg

Note: Specifications are subject to change without notice.

7920/30 Duo
AUTOMATIC TWIN

ADT 7900 series has two facing spindles that can simultaneously dice wafers or packages at high throughput. ADT 7900 series is a high accuracy system that can dice product at high performances and low cost of operation.

Basic machine models:

- 7920 Duo up to 10" X 10"
- 7930 Duo up to 12" X 10" or 12" round

FEATURES & BENEFITS

- Fast & Simple Blade Change
- SECS/GEM platform ready
- Full access to any area of the system for easy maintenance
- Air bearing feed axis (X)
- Fast automatic alignment and cut positioning for increased throughput

Specifications		7920 Duo	7930 Duo
Workpiece Size		10" X 10"	12" X 10" or Ø12"
Spindle		Two facing spindles, Max. 60,000 rpm / 1.2 KW	
Blade Size		2" - 3"	
Y1 / Y2 Axis,	Control	Linear encoder for each Y axis	
	Resolution	0.1 µm	
	Cumulative Accuracy	1.5 µm	
	Indexing Accuracy	1.0 µm	
X Axis		Air Slide	
Z1 / Z2 Axis,	Resolution	0.2 µm	
	Repeatability	1.0 µm	
	Stroke	30 mm (for 2.188" blade OD)	
θ Axis,	Repeatability	4 arc-sec	
	Stroke	350°	
Utilities,	Electrical	200-240 VAC, 50/60 Hz, single phase	
Dimensions	(W x D x H) mm	875 x 975 x 1450	
	Weight	900 kg	

Note: Specifications are subject to change without notice.

ADT = Dicing
Advanced Dicing Technologies

DICING EQUIPMENT

CE

www.adt-co.com

FACTORIES AND R&D CENTER – ISRAEL
ADVANCED DICING TECHNOLOGIES LTD
Hi-Tech Park (south), PO Box 87,
Yokneam 2069202
Tel: 972-4-8545222
Fax: 972-4-8550007
Email: sales@adt-co.com

NORTH AMERICA
ADVANCED DICING TECHNOLOGIES INC.
East Coast Office - Horsham, PA
Tel: 215-773-9155
West Coast Office - Tempe, AZ
Tel: 480-666-9620
Email: ADT-USA-Sales@adt-co.com

CHINA
ADVANCED DICING TECHNOLOGIES LTD.
PuDong, Shanghai, China
Tel: 86-21-5093-9293
Fax: 86-21-5093-9890
Email: china_support@adt-co.com

TAIWAN
ADVANCED DICING TECHNOLOGIES, LTD.
New Taipei City, Taiwan
Tel: 886-2-2608-2027
Fax: 886-2-2608-3710
Email: adt-tw@adt-co.com

Ver. 06/20

71xx 2" AND 4" SPINDLE DICING SYSTEM

The 7120 / 7130 families of 2" and 4" spindle dicing systems deliver a high level of affordability and flexibility to support your needs.

FEATURES & BENEFITS

- Support 2"-3" and 4"-5" blade O.D. with large 'Z' stroke
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

Specifications	7122	7124	7132	7134
Workpiece Size	Ø 8"		Ø12" or 300mm X 300mm W/O frame	
Spindle	60K rpm / 1.2 KW	30K rpm / 2.5KW	60K rpm / 1.2 KW	30K rpm / 2.5KW
Blade Size	2" - 3"	4" - 5"	2" - 3"	4" - 5"
Y Axis, Control	Linear encoder for each Y axis			
Resolution	0.1 µm			
Cumulative Accuracy	1.5 µm			
Indexing Accuracy	1.0 µm			
X Axis	Air Slide			
Z Axis, Resolution	0.2 µm			
Repeatability	1.0 µm			
θ Axis, Repeatability	4 arc-sec			
Stroke	350°			
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase			
Dimensions (W x D x H) mm	965 X 1300 X 1600			
Weight	900 kg			

Note: Specifications are subject to change without notice.

*** Special 7100 XLA available with 2" and 4" spindle covering 24" X 18"**

71MD 2" DICING SYSTEM FOR MEDICAL

The 71MD dicing system is designed for demanding and tight applications such as PZT. The system is equipped with Height on parts measuring system and it can be provided with large Z clearance. It can also be supplied with a balancing tool to minimize spindle vibration, typical for Ultra-Sound sensors applications.

FEATURES & BENEFITS

- Multi Panel handling
- Custom Jigs
- Geometric Model Finder (GMF)
- Large Z clearance
- Low-vibration spindle
- High resolution water flow coolant
- Z Linear encoder
- Height Measuring Tool (HMT)

Specifications	71MD
Workpiece Size	Ø 8"
Spindle	60K rpm / 1.2 KW
Blade Size	2" - 3"
Features	Z Linear encoder Z Clearance Height on parts GMF - Geometrical Model Finder
Y Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
X Axis	Air Slide
Z Axis, Resolution	0.2 µm
Repeatability	1.0 µm
θ Axis, Repeatability	4 arc-sec
Stroke	350°
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W x D x H) mm	965 x 1300 x 1600
Weight	900 kg

Note: Specifications are subject to change without notice.

71TS 2" TILTED SPINDLE

The Tilting Spindle dicing system is designed to meet the needs of Optoelectronic component manufacturers by providing both perpendicular cuts and 8° angular cuts needed to suppress back-reflection in fiber optic components.
The system offers quick changeover from perpendicular (0) to any angle up to 15°.

FEATURES & BENEFITS

- Silicon, Silica-on Silicon
- InP
- Fiber Wave Guides
- Fused Silica
- Polymers on Si
- GaAs
- LiNbO3

Specifications	71TS
Workpiece Size	Ø 8"
Spindle	60K rpm / 1.2 KW
Blade Size	2" - 3"
Features	Two preset angles: - First angle at 0˚C - Second angle at 0˚C-15˚C - Fine angle adjust capability
Y Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
X Axis	Air Slide
Z Axis, Resolution	0.2 µm
Repeatability	1.0 µm
θ Axis, Repeatability	4 arc-sec
Stroke	350°
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W x D x H) mm	965 x 1300 x 1600
Weight	900 kg

Note: Specifications are subject to change without notice.

72xx FULLY AUTOMATIC DICING SYSTEM

The 7200 system offers a wide range of advanced automation and process monitoring option to meet the throughput and quality requirements of your most challenging dicing applications: silicon, glass on silicon, glass, BGA & QFN packages, LTCC, ceramic, PCB and other hard material applications.

FEATURES & BENEFITS

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results

Specifications	7222	7223	7224	7200-300 2"	7200-300 4"
Workpiece Size	Ø 8"			Ø12" or 253mm X 243mm	
Spindle	60K rpm / 1.2 KW		30K rpm / 2.5KW	60K rpm / 1.2KW	30K rpm / 2.5KW
Blade Size	2" - 3"		4" - 5"	2" - 3"	4" - 5"
Y Axis, Control	Linear encoder for each Y axis				
Resolution	0.1 µm				
Cumulative Accuracy	1.5 µm				
Indexing Accuracy	1.0 µm				
X Axis	Air Slide				
Z Axis, Resolution	0.2 µm				
Repeatability	1.0 µm				
θ Axis, Repeatability	4 arc-sec				
Stroke	350°				
Cleaning Station	Full rinse and dry cycle				
Spinning speed	100-2,000 rpm				
Cleaning Method	Atomized cleaning capabilities				
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase				
Dimensions (W x D x H) mm	965 x 1460 x 1700			1100 x 1785 x 1700	
Weight	1200 kg			1350 kg	

Note: Specifications are subject to change without notice.